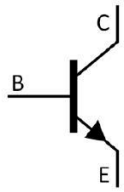
VRW056 ṂṂÞ QSQ ÆṀ ч s ‖ ㄱ Silicon NPN transistor in a SOT-23 Plastic Package.

ｒ ᵇ ҽ ʝ ɔ ķ ṇ / ƍ ᵠ ㇵ Ѿ Ӈ
Small reverse transfer capacitance, low noise figure.

ᵻ ⺓ ļ ѽ ᶻ
High frequency amplifier applications.

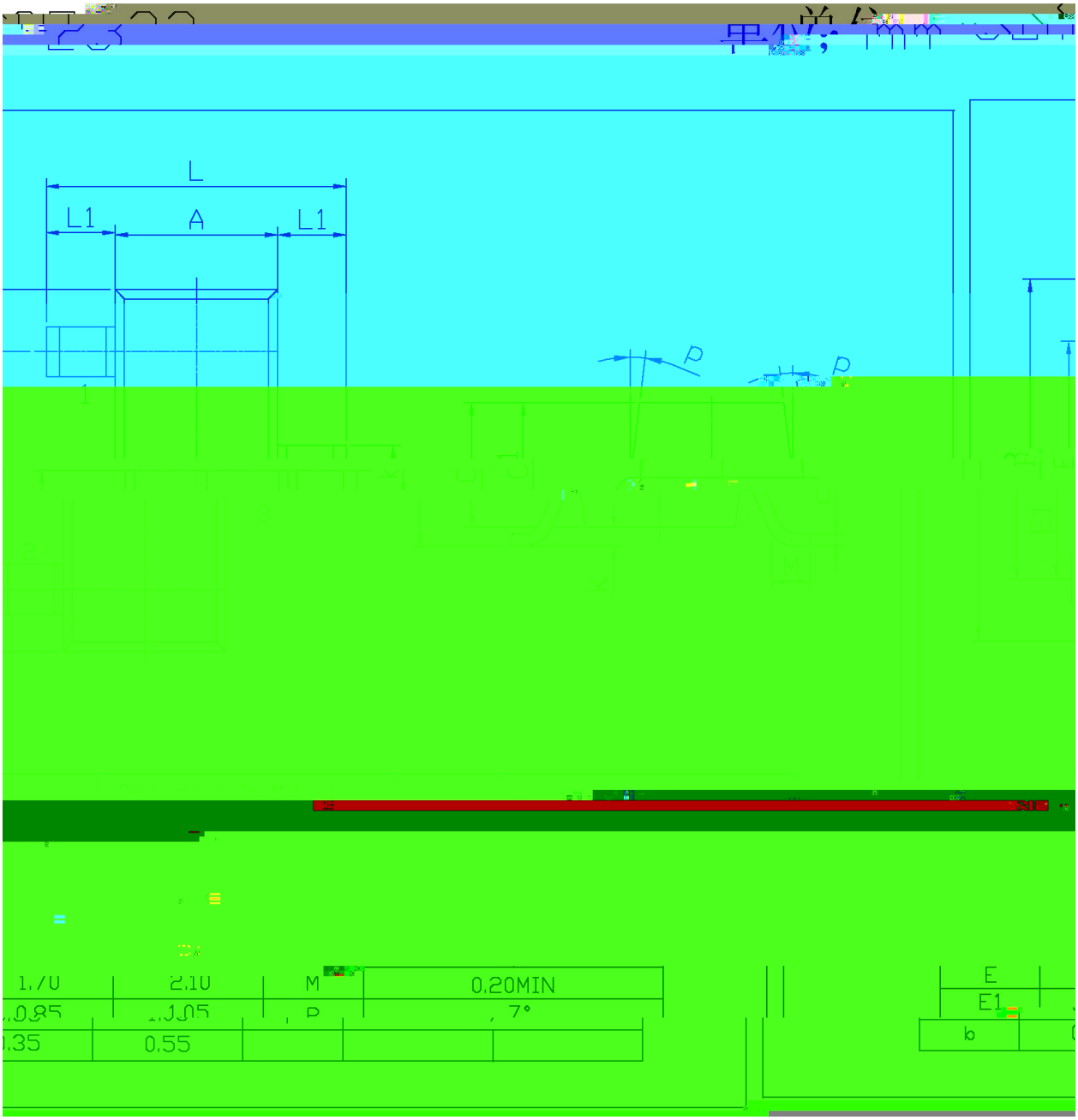




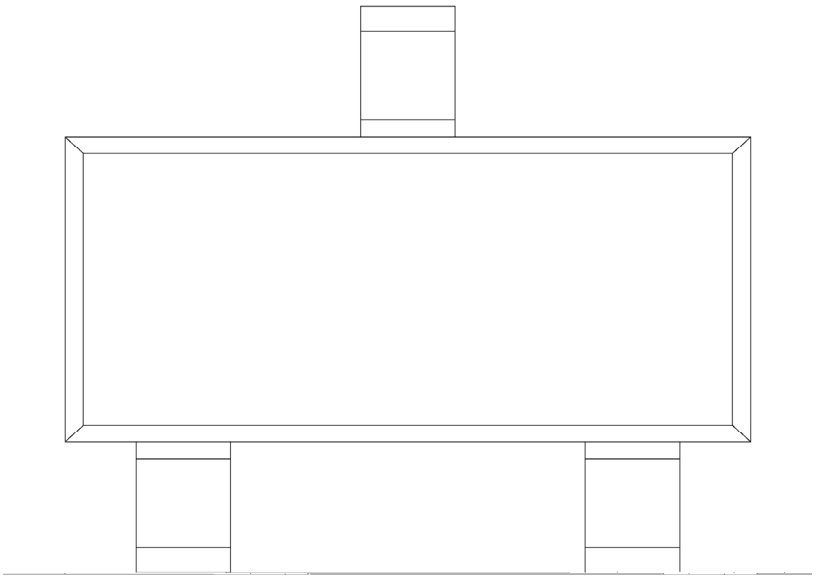
PIN1

v ˝Ω Parameter	ϒ N Symbol	˝Ω Ө Rating	D Ђ Unit
Collector to Base Voltage	V_{CBO}	40	V
Collector to Emitter Voltage	V_{CEO}	30	V
Emitter to Base Voltage	V_{EBO}	4.0	V
Collector Current	I_C	20	mA
Emitter Current	I		

/ Package Dimensions



/ Marking Instructions



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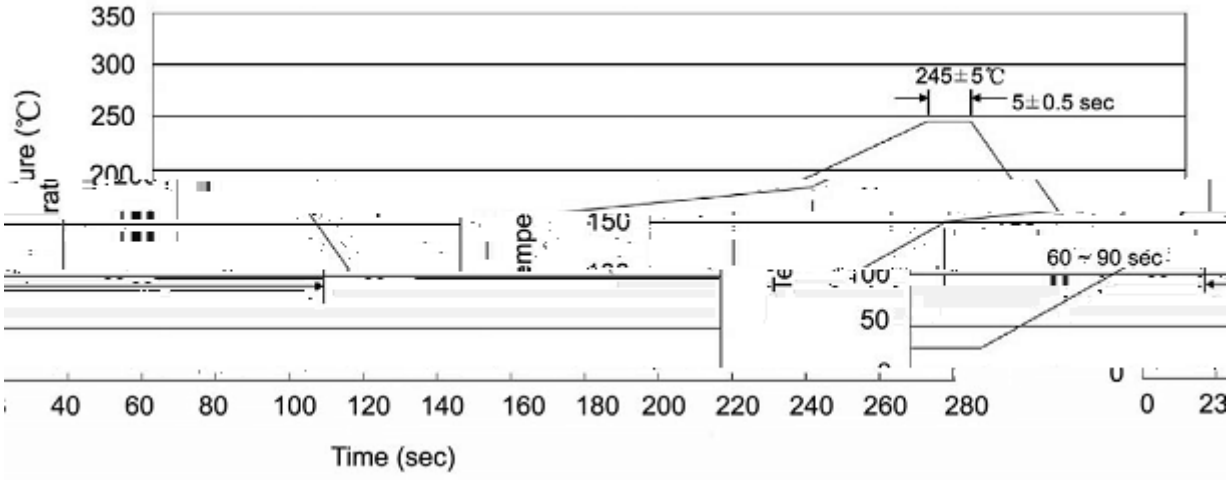
U χ ᠻ h_{FE} ᥢ ᥒᑫ

Note:

K χ Company

7y

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



ب ˝ χ

1 Ĺ ♬ □ ỷ 25 Ḱ 150 ł ı ˋH ڑ 60 Ḱ 90sec;

2 Š Ë □ ỷ 245 ° 5 ł ı ˋH ڑ ˋY ﾊ ㎛ 5 ° 0.5sec;

3 ì ˙ ﾘ ˛ ɔ ﻉ ỷ ㎛ 2 Ḱ 10 ł /sec.

Note:

1.Preheating:25~150 ł , Time:60~90sec.

2.Peak Temp.:245 ° 5 ł , Duration:5 ° 0.5sec.

3. Cooling Speed: 2~10 ł /sec.

/ Resistance to Soldering ❸ Test Conditions

□ ỷ χ 260 ° 5 ł ˋH ڑ χ 10 ° 1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

ɔ ` ﾔ Ł / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm^3)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-23	3,000	10	30,000	6	180,000	7 ×8	180×120×180	390×385×205

/ Notices